LUMIMICRO – TOP LED SPECIFICATION

TOP VIEW LED

Super Luminosity RGB LED

MODEL LMTP50SPRGB-Z

Customer		Model	LMTP50SPRGB-Z	
		Issued Date	2007 - 03 - 29	
Checked By	Approved By	Description	Chip Type RGB LED	
		Written By	Checked By	Approved by
	J			

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Lumimicro co., LTD

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LUMIMICRO TOP LED SPECIFICATION – Futures & Applications& Out line Dimension & Circuit diagram

Features

- [1] Built-in 3 Chip LED
- [2] High-luminosity chip LED
- [3] Using a package with high heat dissipation

Properties, it can be driven with a large current

- [4] Wide viewing angle
- [5] External dimensions: 5.0 x 5.5 x 1.6t mm
- [6] Lead frame package with individual 6 pin

3 LED Chip Die (Red + Green + Blue)

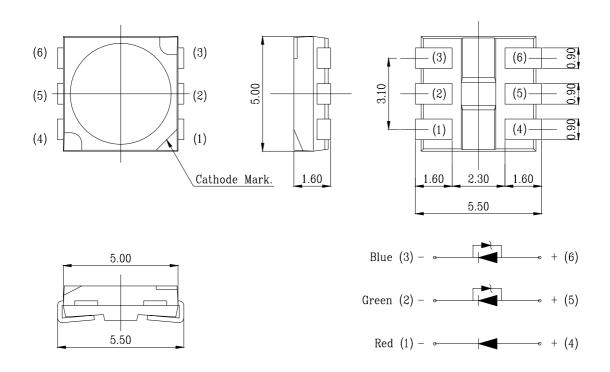
Model : LMTP50SPRGB-Z

Applications

[1] Camera Flash

[2] Hand Carrier Flash

Outline Dimensions & LED Circuit Diagram



Parameter	Symbol	Rating V	alue	Unit
		RED	70	
Power Dissipation	PD	GREEN	100	mW
		BLUE	100	
		RED	30	
Forward Current	IF	GREEN	30	mA
		BLUE	30	
		RED	100	
Forward Pulse Current	IPF	GREEN	100	mA
		BLUE	100	
Reverse Voltage	VR	ALL COLOR	5	V
Operating Temperature	TOT	-30 to +	-85	
Storage Temperature	TST	-40 to +	100	
Soldaring Tomporature	TSD	Reflow: 260	for 10sec	
Soldering Temperature	15D	Hand Soldering: 35	50 for 10sec	

Absolute Maximum Ratings.

* Duty ratio=1/10, Pulse width < 30ms.

Parameter	Symbol	Condition		Min	Тур.	Max	Unit
		IF=20mA/	RED	1.9	-	2.3	
Forward Voltage 1	VF 1	each chip	GREEN	3.0	-	3.4	V
		each emp	BLUE	3.0	-	3.4	
		VR=5V	RED			50	
Reverse Current	IR 1	$\sqrt{K}=3\sqrt{each chip}$	GREEN			50	uA
		/each chip	BLUE			50	
Dominant		IF=20mA/	RED	620	625	630	
Wavelength	d	each chip	GREEN	520	525	530	nm
wavelength		caen emp	BLUE	454	457	460	
	IF 20	IF=20mA/	RED	200	400	-	
Luminous Intensity	IV	each chip	GREEN	600	900	-	mcd
	e	cach chip	BLUE	100	200	-	

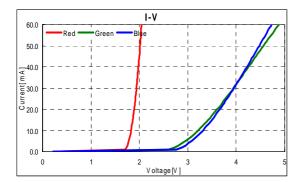
Elector-optical Spec

Parameter	Symbol	Condition	Color	Rank	Min	Тур.	Max	Unit
			RED	RW1	620		625	
Dominant		IF=20mA/	RED	RW2	625		630	
Wavelength	d	each chip	GREEN	GW1	520	-	525	nm
i a orongui		GREEN	UKEEN	GW2	525	-	530	
			BLUE	BW1	454	-	460	
			RED	RL1	200	-	400	
				RL2	400		600	
Luminous	IV	IF=20mA/	CDEEN	GL1	600	-	900	mad
Intensity	each chip	GREEN	GL2	900		1200	mcd	
		BLUE	BL1	100		200		
			BL2	200	-	300		

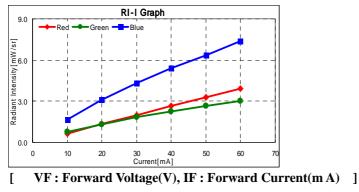
Elector-optical Rank

Electrical & Optical Characteristics

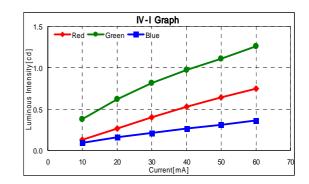
Forward Current vs Voltage



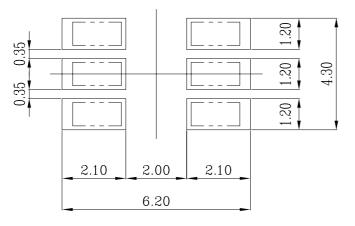




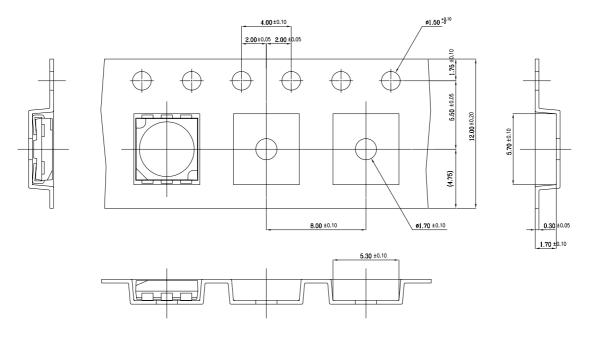
Relative Luminosity vs Forward Current

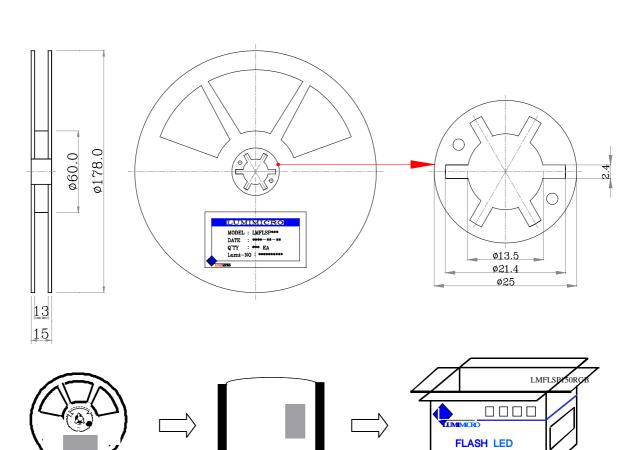


Recommended Pad Pattern



Taping pocket Dimension





Packing Spec

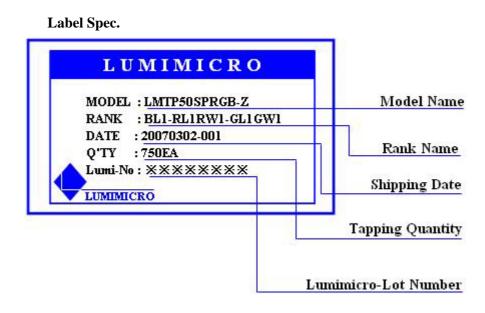
- Aluminum Bag Spec.

	Reel in a Bag	Silica in a Bag	Goods QNT in a Bag
Aluminum Bag	1 Reel	1 Silica	Max : 750ea

- Box packing Spec.

Dimensions(Width/Thickness) Unit : mm		Reels in Box	Goods in QNT in Box	
Box	275/ 285/ 200	10	Max : 7,500ea	

MODEL LMTP50SPRGB-Z



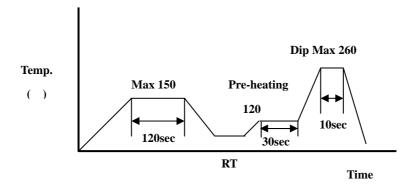
Precautions For Use

- (1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc.
- (2) When washing is required, IPA should be used.
- (3) When the LEDs are illuminating, operating current should be decided after considering the ambient maximum temperature.
- (4) LEDs must be stored to maintain a clean atmosphere. If the LEDs are stored for 3months or more after being shipped from LUMIMICRO, sealed container with a nitrogen atmosphere should be used for storage.
- (5) The LEDs must be dip soldered within seven days after opening the moisture-proof packing. Repack unused Products with anti-moisture packing, fold to close any opening and then store in dry place.
- (6) The appearance and specifications of the product may be modified for improvement without notice.
- (7) This LEDs are sensitive to the static electricity and surge. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If Over voltage which exceeds the absolute maximum rating is applied to LEDs, it will cause damage in LEDs and result in destruction.
- (8) Damaged LEDs will show some unusual characteristics such as remarkably increased leak current, turn-on voltage becomes lower and the LEDs get unlighted at low current.

Reflow Conditions

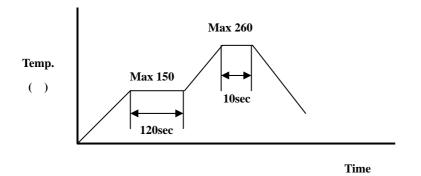
1. Solder Dip Conditions

The Immersion of leads into a solder bath @ MAX 260 shall be to 10 seconds max.



2. Reflow Conditions

Preliminary heating to be at 150 max. for 2 minutes max. Soldering heat to be at 260 max. for 10 seconds max.



3. For Manual Soldering

Not more than 5 seconds @ MAX 300 , under Soldering iron.

	ITEMS	CONDITION	NOTE	Fail/Sample
1	RESISTANCE TO SOLDERING HEAT	TSID=260 , 10sec	2TIMES	0/20
-	(REFLOW SOLDERING)	(PRE TREATMENT 30 , 70%, 168hr)		0/20
2	SOLDERBILITY	TSID=215 ±5 , 3sec	1TIME OVER 95%	0/20
	(REFLOW SOLDERING)	(LEAD SOLDER)	THUE OVER 7570	0/20
3	THERMAL SHOCK	-40 ~ 100 , 15min	20CYCLES	0/20
5		AT EACH TEMP.	20CICLES	0/20
4	MOISTURE RESISTANCE CYCLE	25 ~65 ~-10 ,90%RH	500HRS	0/20
-		24hr/ 1cycle	30011K5	0/20
5	HIGH TEMPERATURE STORAGE	Ta = 100	500HRS	0/20
6	TEMPERATURE HUMIDITY STORAGE	Ta = 60 , RH = 90%	500HRS	0/20
7	LOW TEMPERATURE STORAGE	Ta = -40	500HRS	0/20
8	LIFE TIME 1	25mA /Chip Each@ ROOM TEMP.	500HRS	0/20
9	LIFE TIME 2	15mA /Chip Each@ 60 , 90%RH	500HRS	0/20
		IF = 20mA/Chip Each ,		
10	ON/OFF TEST	Pulse Width 2sec,	100,000CYCLES	0/20
		Duty Ratio 1/2		

Reliability Test Conditions

Failure Criteria

ITEM	SYMBOL	Failure Criteria		
I I IZIVI	STWIDOL	MIN	MAX	
Forward Voltage	VF	-	U.S.L*)×1.2	
C.I.E. x, y	x , y	L.S.L*)×0.8	U.S.L*)×1.2	
Luminous Intensity	IV	L.S.L*)×0.7	-	

U.S.L*) ; Upper Standard Level

L.S.L*) ; Lower Standard Level